

ABSTRACT

In each of ceramic green sheets (2), in the state where the ceramic green sheet is not backed with a carrier film, coil conductor patterns (3) to (7) and lead-out electrodes (8) and (9) are formed by a screen printing method and simultaneously a conductive paste is filled in holes for via hole to form via holes (15). The coil conductor patterns (3) to (7) contain first lands (3a) to (6a) made available at one end of the coil conductor patterns (3) to (7) so as to cover the via holes (15) for connection between layers and second lands (4b) to (7b) to be connected to the via holes (15) made available at the other end. The second lands (4b) to (7b) are larger in diameter than the first lands (3a) to (6a) and it is appropriate that the area of the second lands (4b) to (7b) be 1.10 to 2.25 times as wide as the area of the first lands (3a) to (6a).